Date Created : **2007/12/20**
Date Issued On : **2008/01/30**
PCN# : **Q4075102**

FORECAST CHANGE NOTIFICATION

This is to inform you that a design and/or process change will be made to the following product(s). This notification is for your information and concurrence. This is a preliminary notification. A Final PCN will be issued when qualification is complete and data is available.

If you require data or samples to qualify this change, please contact **Fairchild Semiconductor within 30 days of receipt of this notification.**

If you have any questions concerning this change, please contact:

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Phone:

Implementation of change:
Expected 1st Device Shipment Date: 2008/02/17

Earliest Year/Work Week of Changed Product: D0808

Change Type Description: Mold Compound

Description of Change (From): SOIC-8 FLMP, SSOT-6 FLMP and SC75-6L FLMP package assembly in FSC approved manufacturing locations using non-Green mold compound as shown in table 1:

Description of Change (To): SOIC-8 FLMP, SSOT-6 FLMP and SC75-6L FLMP package assembly in FSC approved manufacturing locations using Green mold compound as shown in table 2:

Reason for Change : Green initiative by Fairchild Semiconductor. Fairchild Semiconductor is dedicated to being a good corporate citizen. All Fairchild Semiconductor products are 2nd level interconnect leadfree and RoHS compliance. The referenced material changes have been made to provide a 'Full Green' (Halogen Free Flame Retardant) package. For additional details on the corporate wide green initiative please visit our Web site at: http://www.fairchildsemi.com/company/green/index.html. Manufacturing will occur at the same assembly facilities producing the current non-green products. Package outline drawings of the affected products remain unchanged. Green products will be fully compliant to all published data sheet specifications and will be interchangeable with current non-green product. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing products.

Qual/REL Plan Numbers : Q20070442

Qualification :

Qualification of Green Mold compound for SOIC-8 FLMP, SSOT-6 FLMP and SC75-6L FLMP.

Change From

BILL OF MATERIALS:

PACKAGE: SOIC-8 FLMP (EMSON)

Location	FSCP
Pin count	8-Leads
Leadframe	C194 SH (Pre-plated NiPd + Au Flash)
Backmetal	TiNiAgAu
Flip Attach	88Pb 10Sn 2Ag NC-SMQ75 FLIP CHIP
Bump	95Pb 5Sn
EMC	Cookson AMC-2RD
Lead Finish	NiPd + Au Flash

PACKAGE: SSOT-6 FLMP (TTR23)

Location	FSCP
Pin count	6-Leads
Leadframe	C194 FH (pre-plated NiPd + Au Flash)
Backmetal	TiNiAgAu
Flip Attach	88Pb 10Sn 2Ag NC-SMQ75 FLIP CHIP
Bump	Pure Copper / 95Pb 5Sn
EMC	Cookson AMC-2RD
Lead Finish	NiPd + Au Flash

PACKAGE: SC75-6L FLMP (TTS23)

Location	FSCP
Pin count	6-Leads
Leadframe	C194 FH (pre-plated NiPd + Au Flash)
Backmetal	TiNiAgAu
Flip Attach	88Pb 10Sn 2Ag NC-SMQ75 FLIP CHIP
Bump	Pure Copper / 95Pb 5Sn
EMC	Cookson AMC-2RD
Lead Finish	NiPd + Au Flash

Change To

BILL OF MATERIALS:

PACKAGE: SOIC-8 FLMP (EMSON)

Location	FSCP
Pin count	8-Leads
Leadframe	C194 SH (Pre-plated NiPd + Au Flash)
Backmetal	TiNiAgAu
Flip Attach	88Pb 10Sn 2Ag NC-SMQ75 FLIP CHIP
Bump	95Pb 5Sn
EMC	Cookson CK5000A
Lead Finish	NiPd + Au Flash

PACKAGE: SSOT-6 FLMP (TTR23)

Location	FSCP
Pin count	6-Leads
Leadframe	C194 FH (pre-plated NiPd + Au Flash)
Backmetal	TiNiAgAu
Flip Attach	88Pb 10Sn 2Ag NC-SMQ75 FLIP CHIP
Bump	Pure Copper / 95Pb 5Sn
EMC	Cookson CK5000A
Lead Finish	NiPd + Au Flash

PACKAGE: SC75-6L FLMP (TTS23)

Location	FSCP
Pin count	6-Leads
Leadframe	C194 FH (pre-plated NiPd + Au Flash)
Backmetal	TiNiAgAu
Flip Attach	88Pb 10Sn 2Ag NC-SMQ75 FLIP CHIP
Bump	Pure Copper / 95Pb 5Sn
EMC	Cookson CK5000A
Lead Finish	NiPd + Au Flash

Qualification Stress Test and Sample Size Detail

Device #1	FDC6036P_F077
Package:	TTR23
#Leads:	006

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
HAST2	X	JESD22-A110	85%RH, 110C, 16V	132	264		77
HTGB		JESD22-A108	150C, 8V	168	500	1000	77
HTRB		JESD22-A108	150C, 16V	168	500	1000	77
PRCL	X	MIL-STD-750-1036	Delta 100C, 2 Min cycle	5000	10000		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Device #2	FDC796N
Package:	TTR23
#Leads:	006

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
HAST2	X	JESD22-A110	85%RH, 110C, 24V	132	264		77
HTGB		JESD22-A108	150C, 20V	168	500	1000	77
HTRB		JESD22-A108	150C, 24V	168	500	1000	77
PRCL	X	MIL-STD-750-1036	Delta 100C, 2 Min cycle	5000	10000		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Device #3	FDJ1027P
Package:	TTS23
#Leads:	006

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
HAST2	X	JESD22-A110	85%RH, 110C, 16V	132	264		45
HTGB		JESD22-A108	150C, 8V	168	500	1000	77
HTRB		JESD22-A108	150C, 16V	168	500	1000	77
PRCL	X	MIL-STD-750-1036	Delta 100C, 2 Min cycle	5000	10000		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Device #4	FDJ129P
Package:	TTS23
#Leads:	006

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
HAST2	X	JESD22-A110	85%RH, 110C, 16V	132	264		45
HTGB		JESD22-A108	150C, 12V	168	500	1000	77
HTRB		JESD22-A108	150C, 16V	168	500	1000	77
PRCL	X	MIL-	Delta 100C, 2	5000	10000		77

		STD-750-1036	Min cycle				
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Device #5	FDS2170N7
Package:	EMSON
#Leads:	008

Precondition Description:

				Read-points	Sample
Stress	P/C	Standard	Conditions		A
PCNL1A		JESD22-A113			0

Environment Stress Detail:

				Readpoints			Samples
Stress	P/C	Standard	Conditions	TP1	TP2	TP3	A
ACLV	X	JESD22-A102	100%RH, 121C	96			77
HAST2	X	JESD22-A110	85%RH, 110C, 42V	132	264		77
HTGB		JESD22-A108	150C, 20V	168	500	1000	77
HTRB		JESD22-A108	150C, 160V	168	500	1000	77
PRCL	X	MIL-STD-750-1036	Delta 100C, 2 Min cycle	5000	10000		77
TMCL1	X	JESD22-A104	-65C, 150C	100	500		77

Product Id Description : This forecast notification covers Fairchild Semiconductor SOIC-8FLMP, SSOT-6 FMLP and SC75-6L FLMP packages. For a complete listing of products covered in this PCN release, please refer to the Affected FSID listing.

Affected FSIDs :

BAS6_BBA002B	FDC3616N	FDC6000NZ
FDC6000NZ_F077	FDC6020C	FDC6020C_F077
FDC6036P	FDC6036P_F077	FDC697P
FDC697P_F077	FDC699P	FDC699P_F077
FDC796N	FDC796N_F077	FDJ1027P
FDJ1028N	FDJ1032C	FDJ127P
FDJ128N	FDJ128N_F077	FDJ129P
FDJ129P_F077	FDS2070N3	FDS2070N7
FDS2170N3	FDS2170N7	FDS3170N7
FDS3170N7_NL	FDS4070N3	FDS4070N7
FDS4072N3	FDS4072N7	FDS4080N3
FDS4080N7	FDS5170N7	FDS6064N3
FDS6064N7	FDS6162N3	FDS6162N7
FDS7060N7	FDS7064N	FDS7064N7
FDS7064SN3	FDS7066ASN3	FDS7066N3
FDS7066N7	FDS7079ZN3	FDS7079ZN3_NL
FDS7082N3	FDS7088N3	FDS7088N7
FDS7088SN3	FDS7088SN3_NL	FDS7096N3
FDS7288N3	FDS7296N3	